



## Application Data Sheet

### Application Information

Application number:: 10619381  
Filing Date:: 07/14/03  
Application Type:: Regular  
Subject Matter:: Utility  
Title:: Low Cost, High Performance Flip Chip Package Structure  
Attorney Docket Number:: CPAC 1015-1  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Total Drawing Sheets:: 5  
Small Entity?:: No

### Applicant Information

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: US  
Status:: Full Capacity  
Given Name:: Rajendra  
Middle Name:: J. D.  
Family Name:: Pendse  
City of Residence:: Fremont  
State or Province of Residence:: CA  
Country of Residence:: US  
Street of mailing address:: 5245 Diamond Common  
City of mailing address:: Fremont  
State or Province of mailing address:: CA  
Country of mailing address:: US  
Postal or Zip Code of mailing address:: 94555

## Correspondence Information

Correspondence Customer Number:: 22470

## Representative Information

Representative Customer Number::	22470	
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## Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Continuation-in-part-of	10084787	02/25/02
10084787	An application claiming the benefit under 35 USC 119(e)	60272236	02/27/01

## Assignee Information

Assignee name:: ChipPAC, Inc.  
Street of mailing address:: 47400 Kato Road  
City of mailing address:: Fremont  
State or Province of mailing address:: CA  
Country of mailing address:: US  
Postal or Zip Code of mailing address:: 94538